

## C1206C519C2TACTU

**Specifications** 

Insulation Resistance

Aliases (C1206C519C2TAC7800) SMD Comm X8G HT150C, Ceramic, 5.1 pF, +/-0.25 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

ee

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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